

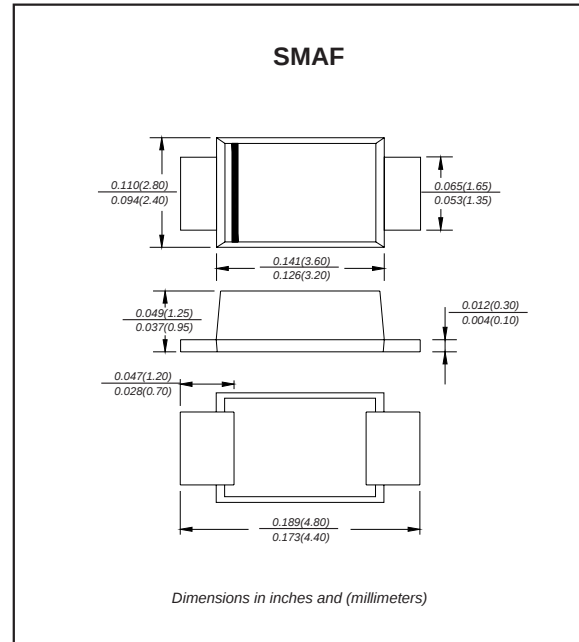
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Compliant to RoHS 2.0
- Compliant to Halogen-free

Mechanical data

- **Case:** JEDEC SMAF molded plastic body
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end
- **Mounting Position:** Any

Package outline

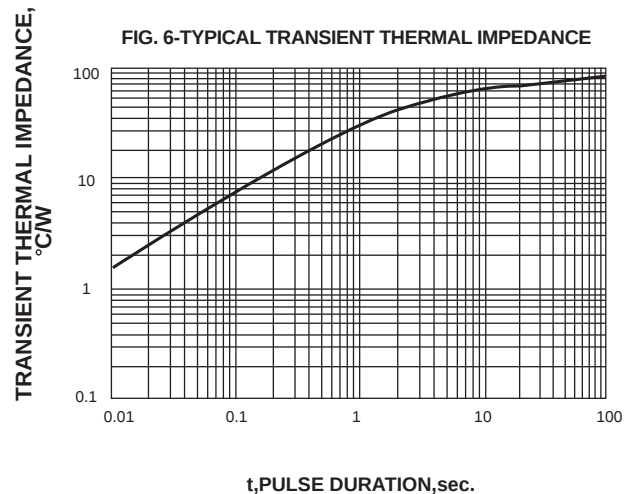
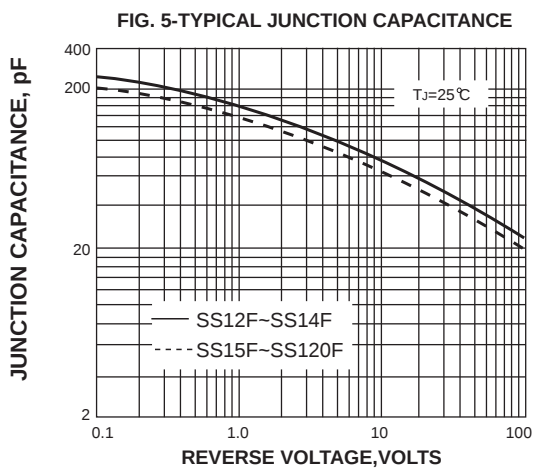
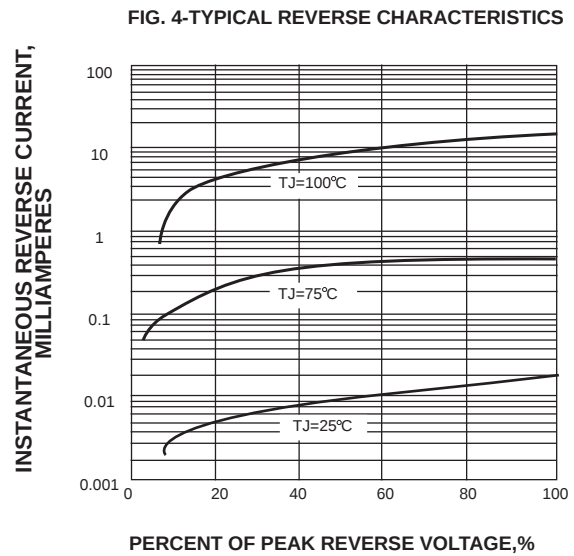
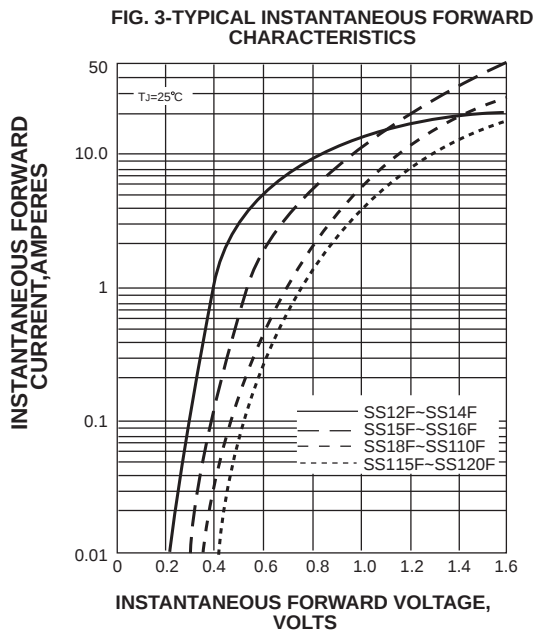
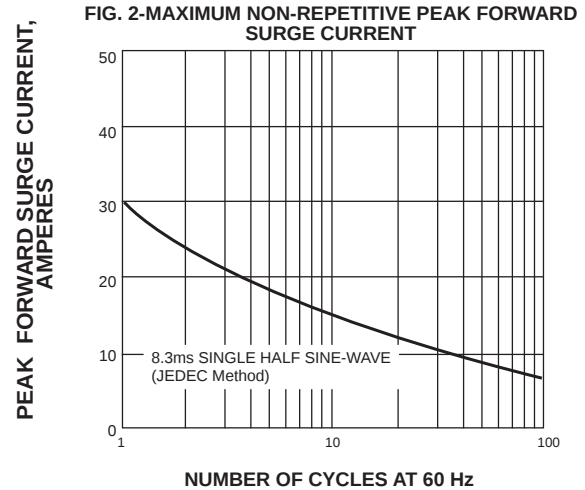
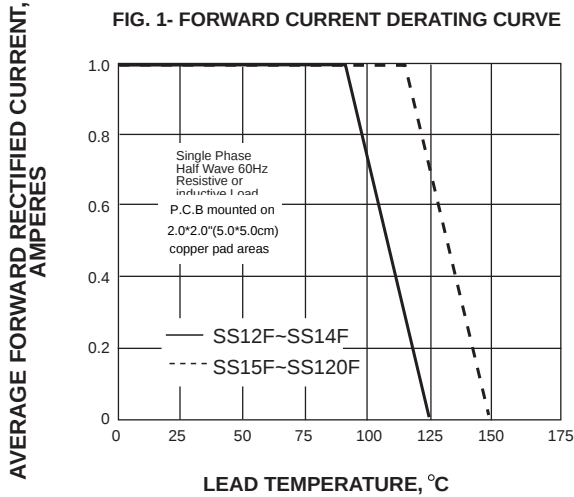


Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	SS14F	SS13F	SS14F	SS15F	SS16F	SS18F	SS110F	SS115F	SS120F	UNITS	
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	150	200	V	
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	105	140	V	
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	150	200	V	
Maximum average forward rectified current at T _L (see fig.1)	I _(AV)	1.0									A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	30.0									A	
Maximum instantaneous forward voltage at 1.0A	V _F	0.55			0.70		0.85		0.95		V	
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =100°C	I _R	0.5					0.1				mA	
		10.0					5.0		2.0			
Typical junction capacitance (NOTE 1)	C _J	110									pF	
Typical thermal resistance (NOTE 2)	R _{θJA}	90									°C/W	
Operating junction temperature range	T _J	-55 to +125				-55 to +150						°C
Storage temperature range	T _{STG}	-55 to +150									°C	

Note:1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

Rating and characteristic curves



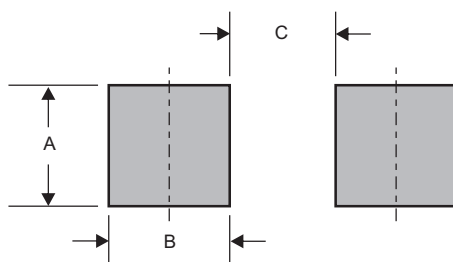
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
SS12F SS13F SS14F SS15F SS16F SS18F SS110F SS115F SS120F	SS12 SS13 SS14 SS15 SS16 SS18 SS110 SS115 SS120	 Marking code

Suggested solder pad layout

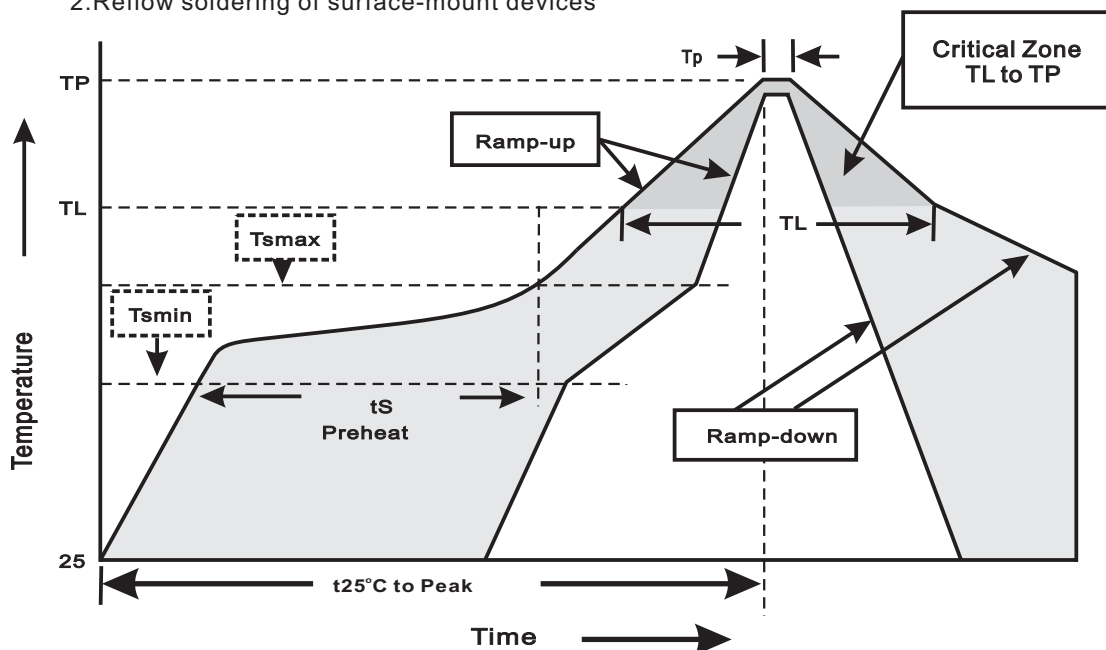


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMAF	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes